PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BRYAN C. HENDRIX	03/12/2014
PHILIP S.H. CHEN	02/18/2014
WEIMIN LI	07/15/2014
DINGKAI GUO	02/17/2014
WOOSUNG JANG	02/08/2014

RECEIVING PARTY DATA

Name:	ADVANCED TECHNOLOGY MATERIALS, INC.
Street Address:	7 COMMERCE DRIVE
City:	DANBURY
State/Country:	CONNECTICUT
Postal Code:	06810
Name:	ATMI KOREA CO., LTD.
Street Address:	KANC 11F 906-10, IUI-DONG, YEONGTONG-GU
City:	SUWON
State/Country:	REPUBLIC OF KOREA
Postal Code:	443-270

PROPERTY NUMBERS Total: 1

Property Type	Number
PCT Number:	US1414954

CORRESPONDENCE DATA

Fax Number: (919)419-9354

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email: hip@hultquistip.com
Correspondent Name: HULTQUIST IP
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ATTORNEY DOCKET NUMBER:	2771-1135 PCT
NAME OF SUBMITTER:	STEVEN J. HULTQUIST

SIGNATURE:	/Steven J. Hultquist/
DATE SIGNED:	07/15/2014

Total Attachments: 9

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ASSIGNMENT

We, **BRYAN C. HENDRIX**, **PHILIP S.H. CHEN**, **WEIMIN LI**, and **DINGKAI GUO**, together with **WOOSUNG JANG**, have made an invention the specification of which is described in the International Patent Application No. PCT/US14/14954 filed under the provisions of 35 U.S.C. § 119, based on United States Provisional Patent Application No. 61/762,352 filed February 8, 2013; United States Provisional Patent Application No. 61/895,380 filed October 24, 2013; and United States Provisional Patent Application No. 61/903,491 filed November 13, 2013, entitled:

"ALD PROCESSES FOR LOW LEAKAGE CURRENT AND LOW EQUIVALENT OXIDE THICKNESS BiTaO FILMS"

We hereby assign to **Advanced Technology Materials, Inc., 7 Commerce Drive, Danbury, CT 06810**, all ownership and rights in:

(i) the invention and International Patent Application;
(ii) non-provisional, continuing, divisional and continuation-in-part applications based on and claiming benefit and/or priority of said International Patent Application; and
(iii) U.S. Patents on the invention.

We are making this assignment based on our business relationship with **Advanced Technology Materials, Inc.**

We respectfully request the Commissioner for Patents of the United States to issue patents on the invention to:

Advanced Technology Materials, Inc.

as co-owner of the invention and aforementioned patent rights.

We agree to execute any other legal documents that may be required to effectuate this Assignment.

We agree that we will promptly communicate to **Advanced Technology Materials, Inc.** all facts which come to our attention affecting the invention or patent rights.

We agree that we will testify in any interference or litigation involving the invention or patent rights.

We declare that we have not done anything in conflict with this Assignment.

3/12/14

BRYAN C. HENDRIX Date (mm/dd/yyyy)

PHILIP S.H. CHEN Date (mm/dd/yyyy)

WEIMIN LI Date (mm/dd/yyyy)

DINGKAI GUO Date (mm/dd/yyyy)

ASSIGNMENT

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BRYAN C. HENDRIX — Date (mm/dd/yyyy)

PHILIP S.H. CHEN — Date (mm/dd/yyyy) 02/18/2014

WEIMIN LI — Date (mm/dd/yyyy)

DINGKAI GUO — Date (mm/dd/yyyy)

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BRYAN C. HENDRIX

Date (mm/dd/yyyy)

PHILIP S.H. CHEN

Date (mm/dd/yyyy)

WEIMIN LI

07/15/2014
Date (mm/dd/yyyy)

DINGKAI GUO

Date (mm/dd/yyyy)

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BRYAN C. HENDRIX
Date (mm/dd/yyyy)

PHILIP S.H. CHEN
Date (mm/dd/yyyy)

WEIMIN LI
Date (mm/dd/yyyy)

02/17/2014

DINGKAI GUO
Date (mm/dd/yyyy)

ASSIGNMENT

I, **WOOSUNG JANG** have made an invention, together with **BRYAN C. HENDRIX, PHILIP S.H. CHEN, WEIMIN LI,** and **DINGKAI GUO**, the specification of which is described in the International Patent Application No. PCT/US14/14954 filed under the provisions of 35 U.S.C. § 119, based on United States Provisional Patent Application No. 61/762,352 filed February 8, 2013; United States Provisional Patent Application No. 61/895,380 filed October 24, 2013; and United States Provisional Patent Application No. 61/903,491 filed November 13, 2013, entitled:

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I am making this assignment based on my business relationship with **ATMI KOREA CO., LTD.**

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ATMI KOREA CO., LTD.

as co-owner of the invention and aforementioned patent rights.

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I agree that I will promptly communicate to **ATMI KOREA CO., LTD.** all facts which come to my attention affecting the invention or patent rights.

I agree that I will testify in any interference or litigation involving the invention or patent rights.

I declare that I have not done anything in conflict with this Assignment.

Woosung Jang
WOOSUNG JANG

02/09/2014
Date (mm/dd/yyyy)